Compact CMP System

Features

- Reasonable initial cost
- Small footprint
- High performance CMP ➔ Know-how from mass production
- Flexible Customization up to user’s requirement
  ➔ From R&D, trial production to mass production
- 2”~8” polishing head available, multiple size of wafers are polishable in one system.
- Mounting of wafer loader enables full-automatic operation
- Mounting of cleaning unit enables precise cleaning
Air-float Head "Sylphide"

- Air film formation provides very uniform pressure distribution in the wafer plane.
- Possession of an airbag independent of an air film provides low-pressure stability.
- An independent retainer pressure airbag provides excellent edge profile control.
- One-touch replacement of retainer/membrane reduces downtime (see below).
- Addition of zone control function is available (optional).

Optical End-Point Detection System

- Uses white light source and accurately detects residual film changes with reflection data of wide wavelength range and special algorithm.
- Provides a wide range of applications.

Various optional functions for mass production are available.